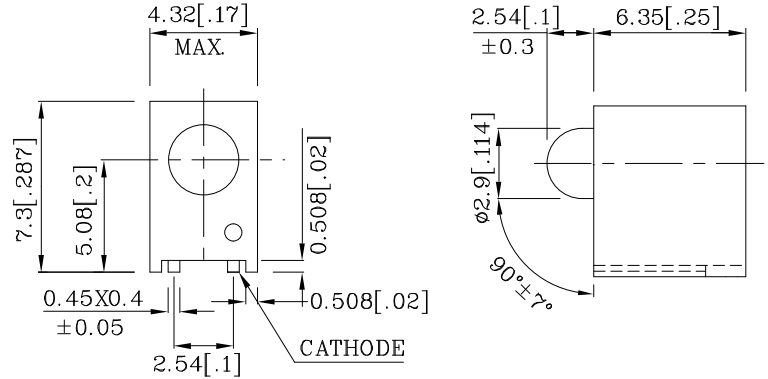


Features

- I.C. COMPATIBLE.
- BLACK CASE ENHANCES CONTRAST RATIO.
- WIDE VIEWING ANGLE.
- HIGH RELIABILITY LIFE MEASURED IN YEARS.
- HOUSING MATERIAL: PPA
- PACKAGE : 500PCS / REEL.
- HIGH TEMPERATURE RESISTANT HOUSING.
- HIGH GLASS TRANSITION TEMPERATURE EPOXY.
- RoHS COMPLIANT.



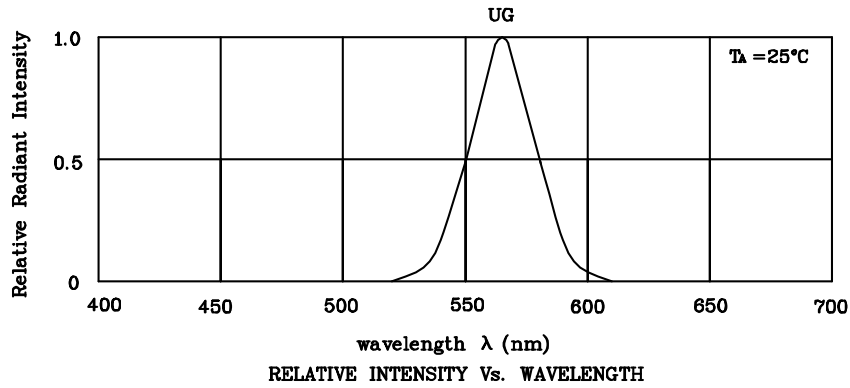
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. Specifications are subject to change without notice.

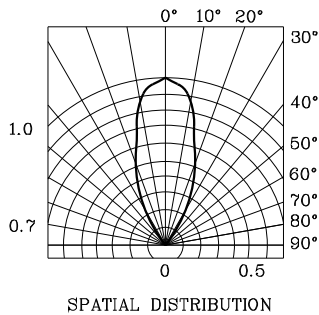
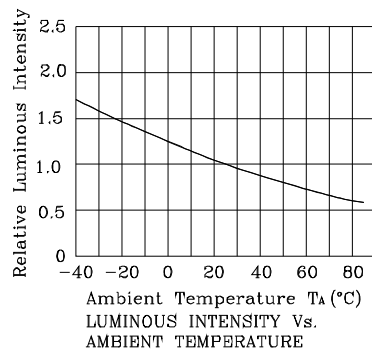
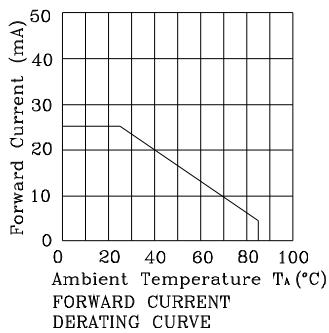
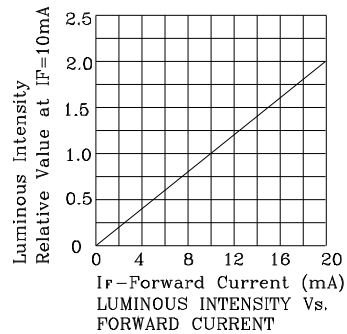
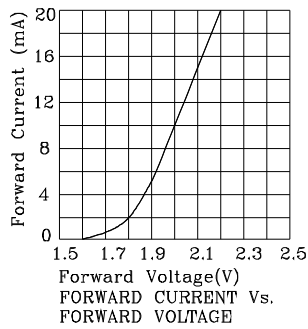
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		UG (GaP)	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	140	mA
Power Dissipation	P_T	62.5	mW
Operating Temperature	T_A	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics ($T_A=25^\circ\text{C}$)		UG (GaP)	Unit
Forward Voltage (Typ.) ($I_F=10\text{mA}$)	V_F	2.0	V
Forward Voltage (Max.) ($I_F=10\text{mA}$)	V_F	2.5	V
Reverse Current (Max.) ($V_R=5\text{V}$)	I_R	10	uA
Wavelength of Peak Emission (Typ.) ($I_F=10\text{mA}$)	λ_P	565	nm
Wavelength of Dominant Emission (Typ.) ($I_F=10\text{mA}$)	λ_D	568	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=10\text{mA}$)	$\Delta\lambda$	30	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	15	pF

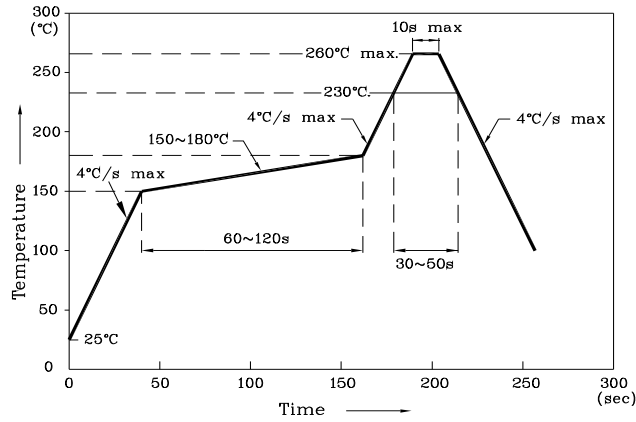
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ($I_F=10\text{mA}$) mcd		Wavelength nm λ_P	Viewing Angle 2θ 1/2
				min.	typ.		
XNK1LUG147DSMD	Green	Gap	Green Diffused	8	19	565	40°
Published Date : JAN 18,2008 Drawing No : XDSB1698 V1 Checked : B.L.LIU P.1/4							



❖ UG



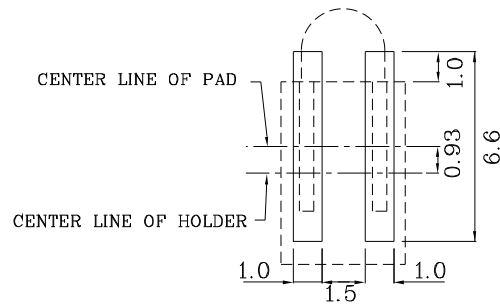
Reflow Soldering Profile For Lead-free SMT Process.



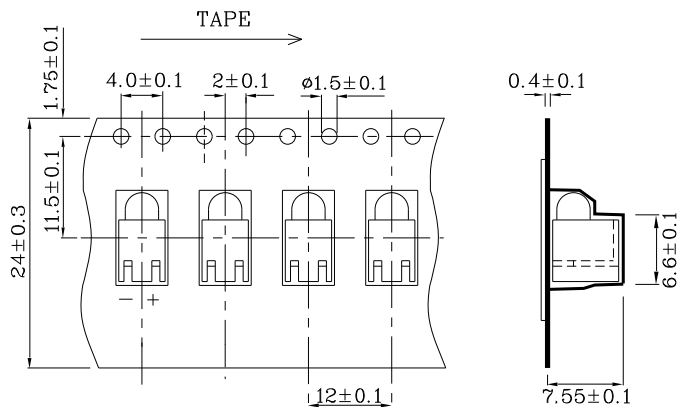
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units: mm ; Tolerance: ± 0.1)

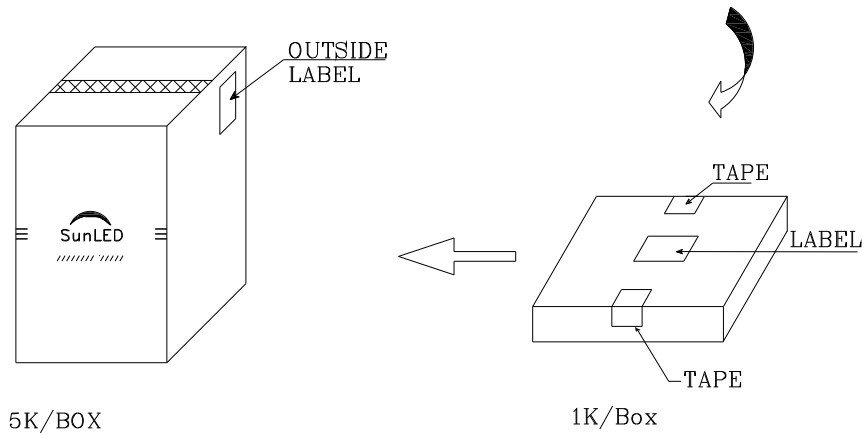
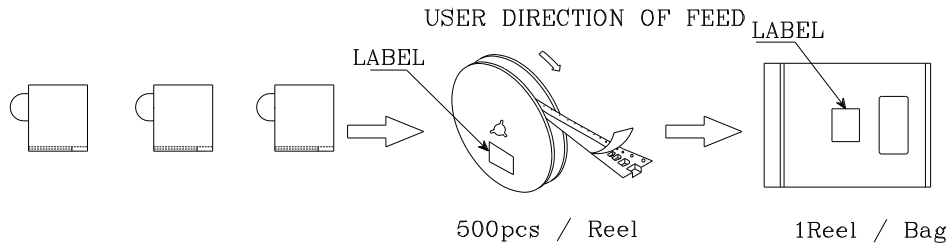



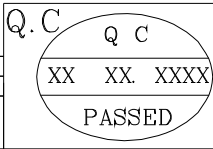


❖ Tape Specification (Units : mm)



PACKING & LABEL SPECIFICATIONS

XNK1LUG147DSMD

	
P/NO : XNK1Lxx147x	
QTY : 500 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	